



Material Content Data Sheet



Sales Product Name				IPD70N10S3L-12		Issued		24. January 2018	
MA#				MA001391454					
Package				PG-TO252-3-11		Weight*		377.18 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	5.833	1.55	1.55	15465	15465	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		571		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		171		
	non noble metal	copper	7440-50-8	215.017	57.00	57.08	570067	570809	
wire	non noble metal	aluminium	7429-90-5	38.730	10.27	10.27	102683	102683	
encapsulation	organic material	carbon black	1333-86-4	0.896	0.24		2375		
	plastics	epoxy resin	-	15.677	4.16		41563		
	inorganic material	silicondioxide	60676-86-0	73.008	19.36	23.76	193564	237502	
leadfinish	non noble metal	tin	7440-31-5	3.740	0.99	0.99	9916	9916	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		241		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	242	
solder	noble metal	silver	7440-22-4	0.118	0.03		312		
	non noble metal	tin	7440-31-5	0.094	0.02		249		
	non noble metal	lead	7439-92-1	4.493	1.19	1.24	11911	12472	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.08	5.09	50845	50911	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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